

ABSTRACT

A method for producing a light-emitting device comprising: a step of electrically connecting a first electrode provided on one main surface of a semiconductor substrate (element substrate) through a light-emitting layer, and a first lead of a lead frame, so as to oppose each other; a step of electrically connecting a second electrode provided on the rear surface of a surface provided with the light-emitting layer of said element substrate, and a second lead of the above-described lead frame; a step of encapsulating a connecting part of said first electrode and said first lead, and said second electrode, and an electrode part of the second lead, with a transparent resin; and a step of producing a discrete edge by cutting said first lead and the second lead from said lead frame; wherein a film of joining material (joining material film) made of an alloy or a single metal, is formed on the first electrode of said light-emitting element, and a pattern to reduce spreading of said joining material is formed on an element mounting part of said first lead, in advance of the step of electrically connecting the first electrode of said light-emitting element and said first lead, to reduce amount of the joining material flowing outside of a joining area wherein the first electrode is placed.